



Q2 2025

Market Insights



Rebound
Electronics

Semiconductor Industry Market Outlook



Global Semiconductor Outlook Q3 2025: Revenue Surge, Memory Spike, and Strategic Shifts

The global semiconductor industry enters Q3 2025 with strong momentum, riding on a surge in AI-related demand, memory market revival, and aggressive capital expenditure across regions. With geopolitical forces shaping supply chains and price dynamics, industry players are navigating a complex but highly rewarding growth cycle.

Market Growth & Regional Dynamics

The global semiconductor market is projected to reach **US \$755 billion in 2025**, up from **US \$681 billion in 2024**, marking a robust **11% year-over-year growth**. According to Gartner and WSTS, this surge is driven primarily by logic, memory, and the relentless expansion of AI infrastructure across data centers and edge devices.

Regionally, the Americas and Asia-Pacific are leading growth:

- **Americas:** Expected to expand by 12 - 14%, fuelled by CHIPS Act investments and large-scale fab construction.
- **Asia-Pacific:** Maintains growth dominance with TSMC, Samsung, and Chinese fabs scaling advanced process nodes.
- **Europe:** Lags slightly behind, with subdued growth amid slower automotive chip recovery.

Memory Market: DRAM & HBM Pricing in Focus

Memory has become a focal point of Q3 2025, especially with AI accelerating demand for both bandwidth and density.

- **DRAM prices** are expected to surge between **30% and 45%**, particularly for DDR4 and GDDR6 chips. Meanwhile, **DDR5 and LPDDR5X** are forecast to rise by a more moderate **3 - 10%**, according to industry analysts of Tom's Hardware.
- **High-Bandwidth Memory (HBM)** demand is outstripping supply. Micron reported sold-out HBM inventory through the rest of 2025 and guided **Q3 revenue at US \$8.8 billion** - a direct result of generative AI's memory appetite according to report from Reuters.
- The **HBM market** is growing at a staggering **57.5% CAGR**, projected to rival traditional server DRAM in market share by 2028 (PwC Semiconductor Outlook).

Passive Components: Quiet Backbone, Steady Gains

Often overlooked, the **passive components market** - including capacitors, resistors, and inductors - is poised for consistent growth.

- The global market is expected to grow from **US \$50 billion to US \$66 billion by 2030**, at a steady 5 - 6% CAGR, according to John Rector Analysis.
- **Resistors and capacitors** are experiencing high volume demand in EVs, industrial systems, and telecom infrastructure. According to TTI MarketEye, resistors are currently leading passive demand in 2025, while inductors face slight volume contraction.
- While **gross margins** remain modest (~10 - 15%), passive components remain critical to the bill of materials in nearly every semiconductor design based from Passive-Components.eu report.

CHIPS, Localisation & Node Race

Geopolitical forces continue to reshape the global semiconductor map through aggressive **fab localization strategies** and investment in next-gen nodes.

- **China** is set to lead global fab investment in 2025 with **~US \$38 billion** in capex, followed by Taiwan and South Korea at ~US \$21 billion each. The **United States and Japan** are committing ~US \$14 billion respectively, according to reports from Reuters.
- **CHIPS and K - CHIPS Acts** are directly supporting infrastructure and R&D, particularly in advanced packaging and 2 nm+ process development.
- TSMC and Samsung are now ramping 3 nm production while working toward 2 nm commercial readiness by late 2025.

Emerging Trends for Q3 2025

- **Memory Pricing Power Returns**
Older memory formats (DDR4, GDDR6) see strong price spikes - driven by constrained supply and broad demand across legacy devices and AI servers.
- **AI Infrastructure Dominates Demand**
AI chips, DRAM, and HBM continue to dominate capex decisions, pushing forward not just logic but also memory and passive component procurement.
- **Fab Expansion Redefines Global Competition**
Localised mega-fab strategies are redefining national semiconductor capacity - blurring the traditional East-West supply dynamic.
- **Advanced Packaging Goes Mainstream**
Heterogeneous integration and chiplet architecture adoption require more sophisticated passive components and packaging techniques.
- **Trade Policy Risks Remain**
U.S. - China tension, export controls, and tariff threats continue to cast uncertainty, particularly for memory and analog device exporters.

Q3 2025 Forecast Summary

Segment	Q3 Trend	2025–26 Outlook
DRAM & HBM	w+30 - 45% price surge (legacy & AI)	Tight supply, sustained growth
NAND Flash	Recovery underway, +23% CAGR	QLC & AI integration accelerating demand
Passive Components	Stable 5 - 6% CAGR	High volume, low margin, mission-critical
Foundry Investments	Record global capex in Q3/Q4	Scaling 3 nm and prepping 2 nm
Chips/Localisation	U.S., China, Korea lead regional reshoring	Competitive node development & packaging

Q3 2025 sets a high - stakes stage for the global semiconductor industry. From DRAM price swings to billion-dollar national fab strategies, the industry is no longer just cyclical - it's strategic. Memory will define pricing power, passive components will support system density, and capital expenditure will solidify long-term leadership.

For those watching the supply chain, this quarter is about agility, diversification, and AI-readiness. The winners of Q3 will be those who not only scale but also strategise across geographies, technologies, and architectures.

Largest Companies by Market Capitalisation in the Industry (Q2 2025)

Name	Market Cap (in USD)
NVIDIA	4.001T
Broadcom Inc.	1.296T
TSMC	1.186T
ASML	317.20B
Samsung	304.56B
AMD	237.11B
Texas Instruments	199.90B
QUALCOMM	169.41B
Applied Materials	158.17B
Arm Holdings	153.10B

Company Specific Updates

AMD

- AMD is preparing the Ryzen 5 9600X3D, a 6-core Zen 5 chip with 96 MB 3D V-Cache, to boost gaming performance in the mid-range market and rival Intel's i5-14600K and 245K.
 - AMD stock jumps 4% following HSBC's bullish upgrade and rising investor optimism, with price targets now eyed at \$150–160 ahead of Q2 earnings on August 5.
 - AMD warns of new Meltdown- and Spectre-like "Transient Scheduler Attack" vulnerabilities affecting a wide range of CPUs, urging patches despite their low severity due to critical security implications flagged by experts.
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Analog Devices

- Goldman Sachs initiates coverage of Analog Devices (ADI) with a Buy rating and \$285 price target, citing cyclical recovery and strong supply chain management in the analog semiconductor sector.
 - Analog Devices forecast Q3 revenue above expectations at \$2.75B, driven by tariff-related pull-ins in auto and consumer demand, though auto sales are expected to decline sequentially, spooking investors.
 - Analog Devices launches ADVentures, its first corporate VC fund, to back early-stage startups in robotics, climate tech, human health, AI, and next-gen computing globally.
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Broadcom

- Broadcom's aggressive VMware licensing changes have sparked global legal disputes with Siemens, AT&T, United Healthcare, and the Dutch government over support and perpetual rights.
 - Broadcom has begun shipping its Tomahawk 6 networking chip, doubling performance to support massive AI data centers using Ethernet and chiplet-based design on TSMC's 3nm process.
 - Broadcom repaid \$6B in outstanding loans from its 2023 credit facility using proceeds from a \$6B senior notes sale, retiring all obligations ahead of the 2028 maturity.
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Diodes Inc.

- Diodes Incorporated has launched the industry's first PCIe 6.0-compliant ReDriver, the PI3EQX64904, enabling 64GT/s PAM4 signal speeds with enhanced signal integrity for AI data centers, HPC, and networking applications.
 - Diodes Incorporated has introduced the AH4930Q, its first automotive-compliant 12-bit I2C 3D linear Hall-effect sensor for precise, contactless rotary motion and proximity detection in systems like infotainment controls and gear shifters.
 - Diodes Incorporated has launched its first InSb Hall element sensors - AHE300 and AHE10x series - offering ultra-high sensitivity and low offset for accurate rotation and current detection in consumer and industrial applications.
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Infineon

- Infineon will begin 300 mm GaN wafer production in Q4 2025, seizing market share as TSMC exits the GaN space and aiming to meet booming demand with 2.3x higher chip yield than 200 mm processes.
 - Infineon has launched its third-gen XENSIV™ 3D magnetic Hall-effect sensors for precise position detection in automotive, industrial, and consumer applications, offering ASIL-B safety, wide temperature tolerance, and low power operation.
 - IDEMIA Secure Transactions and Infineon Technologies have formed a strategic partnership to revolutionize digital car access with secure, scalable, and post-quantum-ready automotive solutions.
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Intel

- Intel may scrap its 18A process node for foundry customers and shift focus to 14A, potentially leaving TSMC's N2 and A16 nodes without direct competition in the near term.
 - Intel's next-gen "Nova Lake-S" client CPU has taped out on TSMC's 2nm (N2) node, signalling a hybrid manufacturing strategy with Intel's 18A process - likely a contingency plan for yield or capacity, with launch expected in H2 2026.
 - Intel's RealSense spins off as standalone firm, raises \$50M to expand AI vision tech for robotics, with plans to scale depth camera production, AI R&D, and global reach.
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Kyocera

- Kyocera launches compact, air-cooled G7A Series UV LED light source, delivering top-class 20W/cm² irradiance and customisable widths for high-speed, eco-friendly curing in tight spaces.
- KYOCERA AVX unveils DB0402 3dB 90° hybrid couplers for 3 - 4.1GHz RF systems, offering compact, high-power, low-loss performance ideal for 5G, automotive, and industrial wireless applications.
- KYOCERA AVX launches 9155-900 Series vertical-mate battery connectors, offering robust, damage-resistant power connectivity ideal for automotive, industrial, and consumer devices requiring high-cycle, space-saving designs.

Lattice

- Lattice Semiconductor has been named to TIME's 2025 list of America's Best Mid-Size Companies, recognizing its innovation, employee satisfaction, and sustainability efforts.

Murata

- Murata has launched the world's first high-frequency XBAR filter, delivering low-loss, high-attenuation performance for 5G, Wi-Fi 7, and future 6G networks.
- Murata has become the first in the electronic component manufacturing industry to implement a closed-loop recycling system for silver used in EMI filters, advancing its commitment to a sustainable, resource-efficient society.

Nexperia

- Nexperia has introduced two 1200 V, 20 A SiC Schottky diodes (PSC20120J and PSC20120L), offering ultra-low loss, temperature-independent switching and surge-resilient performance ideal for high-efficiency AI server, telecom, and solar inverter power systems.
 - Filinvest-ENGIE Renewable Energy Enterprise Inc. has completed a 3MWp solar rooftop project for Nexperia Philippines in Laguna, marking a key milestone in expanding industrial clean energy solutions and supporting the country's low-carbon transition.
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NVIDIA

- Nvidia has become the first publicly traded company to surpass a \$4 trillion market cap, driven by explosive AI chip demand - catapulting CEO Jensen Huang's net worth to \$140 billion, up \$25 billion year-to-date.
- Nvidia's first desktop PC chip, the GB10 Grace Blackwell, officially launches July 22 in Asus' Ascend GX10 mini-PC - aimed at AI workstation and edge deployments with 1 PFLOP AI performance, though pricing and full availability remain undisclosed.

NXP

- NXP's new 18-channel BMx7318/7518 battery cell controller ICs enhance EV and energy storage system performance by integrating advanced ADCs, high-current balancing, and safety features while cutting external components by 50%.
- NXP has introduced the IW693 Wi-Fi 6E SoC with 2x2 MIMO and Bluetooth for industrial IoT and smart home applications, offering advanced wireless features, security enhancements, and flexible connectivity options without 802.15.4 support.
- NXP plans to shut four 8-inch fabs, including its largest in the Netherlands, as it transitions to advanced 12-inch wafer production.

Onsemi

- ON Semiconductor's 80% rally from April lows may be over as weak signals from key supplier Aehr and major customer Tesla, combined with ongoing pricing pressure and margin contraction, suggest a challenging outlook for its auto and EV-driven business.
 - Onsemi has withdrawn its \$6.9 billion bid to acquire Allegro MicroSystems after the latter rejected multiple offers as inadequate.
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Panasonic

- Panasonic Energy has launched mass production at its new Kansas lithium-ion battery factory - one of North America's largest EV battery plants - aiming for 32 GWh annual output to meet rising U.S. electric vehicle demand and strengthen domestic supply chains.
 - Panasonic's planned ¥118.5 billion (\$807 million) sale of its projector business to Orix has collapsed after both parties failed to reach final agreement on terms.
 - Panasonic has launched the Aquarea DHW Heat Pump, a propane-based system capable of heating water up to 65 °C using ambient air, offering high energy efficiency, multiple configurations, and compatibility with PV systems and hybrid setups.
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Rapidus

- Japan's METI plans to invest ¥100 billion in Rapidus with a golden share condition to retain veto rights over key decisions, reinforcing national control as the company targets 2nm chip mass production by 2027 with total funding needs of ¥5 trillion.
 - Honda is reportedly planning to invest in Rapidus to strengthen its domestic semiconductor supply chain for automated driving systems, supporting the chipmaker's goal of mass-producing 2nm chips by 2027 amid growing public-private funding efforts.
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Renesas

- Renesas' RA2T1 microcontroller, powered by a 64MHz Arm® Cortex®-M23 core, is designed for low-end motor control in compact devices like power tools and fans, offering advanced analog features, wide voltage support, and scalable development tools for rapid prototyping and evaluation.
 - Renesas has launched new 650V Gen IV Plus GaN FETs optimised for high-efficiency, high-density power conversion in AI data centers, EV charging, and industrial systems, offering superior performance, compact packaging, and seamless integration with standard silicon gate drivers.
 - Mouser Electronics is now stocking Renesas's ultra-compact DA14535 SmartBond TINY Bluetooth 5.3 SoC - based on a Cortex-M0+ MCU with integrated 2.4 GHz radio in a 2.2 × 3 mm package - ideal for low-power IoT, medical disposables, wearables, and sensor applications.
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Samsung

- Samsung Austin Semiconductor has invested \$1 million into Taylor ISD's career and technical education program to support workforce development for the semiconductor industry in Central Texas.
 - Samsung has delayed its 1.4nm chip production to 2029 and is refocusing on stabilizing 2nm manufacturing by late 2025 to improve yields, restore client trust, and address deepening financial losses in its foundry business.
 - Samsung Semiconductor India Research (SSIR) has launched its first Samsung Skill Development Centre at Government Polytechnic KGF in Karnataka, establishing five advanced labs focused on AI/ML, automation, robotics, cybersecurity, and engineering to equip students in rural India with industry-ready skills and support the country's digital empowerment and innovation goals.
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Siemens

- Siemens has been awarded a contract to supply Communications-Based Train Control (CBTC) and telecommunications systems for Phase 2 of the Nagpur Metro project in India, building on its involvement since the network's initial launch in 2019.
 - Siemens and SAP CEOs have called on the European Union to revise its AI legislation, warning in Frankfurter Allgemeine Zeitung that current rules risk stifling innovation and should be restructured to better support technological progress.
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ST Microelectronics

- STMicroelectronics and Metalenz have signed a new license agreement to expand the adoption of metasurface optics, combining ST's 300 mm semiconductor-optics platform with Metalenz's IP to drive high-volume, next-gen applications in consumer, industrial, and automotive sensing.
 - STMicroelectronics plans to reduce its workforce by 5,000 over the next three years through a combination of 2,800 announced job cuts and around 2,000 additional departures via attrition and voluntary exits, according to CEO Jean-Marc Chery.
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Toshiba

- Bain Capital led a consortium to acquire Toshiba Memory Corporation, ensuring its technology and operations remain in Japan while attracting major U.S. tech investors under restricted governance terms.
 - Toshiba has completed delivery of four 350MW hydro turbines and generators for China's Ninghai Pumped-Storage Power Plant, now fully operational to support renewable energy integration and grid stability.
 - Toshiba America Business Solutions has secured a new national cooperative contract with Region 4–ESC through OMNIA Partners, enabling U.S. schools, universities, nonprofits, and government entities to access discounted pricing on its technology products and services.
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Texas Instruments

- Texas Instruments has announced a historic \$60 billion investment to expand semiconductor manufacturing across Texas and Utah, aligning with U.S. efforts to boost domestic chip production and create 60,000 jobs.
 - UBS has raised its price target on Texas Instruments to \$255 from \$245 while maintaining a Buy rating.
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TSMC

- TSMC is delaying its second Japan plant to fast-track U.S. investments and avoid potential Trump-era semiconductor tariffs, prioritising Arizona expansion amid shifting geopolitical pressures.
 - TSMC faces an expanded U.S. class-action lawsuit with over 30 plaintiffs alleging racism, discrimination, and unsafe working conditions at its Arizona fab, including claims of bias against American workers and disturbing incidents of workplace harassment.
 - TSMC reported June 2025 revenue of NT\$263.71 billion, down 17.7% from May but up 26.9% year-over-year, with H1 2025 revenue rising 40% to NT\$1.77 trillion.
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Vishay

- Vishay, TDK, and Murata unveiled next-gen passive components - GHz-ready resistors, high-current inductors, and the world's smallest 10 μ F/50 V MLCC -enabling more compact, high-performance designs for automotive and RF systems.
 - Vishay has introduced three new compact 650V and 1200V Gen 3 SiC Schottky diodes in SlimSMA HV packages, offering high efficiency, fast switching, and enhanced thermal and electrical isolation for space-constrained, high-voltage power applications.
 - Vishay has launched the SiEH4800EW 80V power MOSFET in a compact PowerPAK 8x8SW package, offering ultra-low on-resistance, superior thermal performance, and enhanced solderability for high-efficiency industrial power applications.
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Analog

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Analog Devices	Sensors	10 - 26	↔	↔	
ams	Sensors	10 - 26	↔	SMA	
Bosch Sensortec	Sensors	10 - 14	↔	↔	
Diodes Incorporated	Multi- Source Analog/Power	12 - 20	↔	↔	
	Switching Regulators	12 - 20	↔	↔	
FTDI Chip	Interface	12 - 16	↔	↔	
Infineon	Sensors	06 - 28	↔	↔	
	Switching Regulators	16 - 26	↔	↔	
	Analog and Power for Automotive (CAN/LIN/Smart FET)	22 - 26	↔	↔	
Maxlinear	Interface	22 - 28	↗	↔	
Melexis	Sensors	14 - 62	↔	SMA	
Microchip	Signal Chain (Amplifiers and Data Converters)	06 - 12	↔	↔	
	Timing	10 - 14	↔	↔	
	Switching Regulators	10 - 23	↔	↔	
Monolithic Power Systems	Switching Regulators	14 - 26	↔	↔	
NXP	Sensors	18 - 54	↔	↔	
	Interface	18 - 22	↔	↔	
	Analog and Power for Automotive (CAN/LIN/Smart FET)	18 - 22	↔	↔	
Onsemi	Sensors	20 - 54	↔	SMA	
	Signal Chain (Amplifiers and Data Converters)	12 - 22	↔	↔	
	Timing	24 - 34	↗	↔	
	Multi- Source Analog/Power	12 - 22	↔	↔	
	Switching Regulators	12 - 22	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Panasonic	Sensors	18 - 28	↔	↔	
Pericom Saronix-eCera	Timing	18 - 28	↗	↔	
Power Integrations	Switching Regulators	18 - 20	↔	↔	
Renesas	Signal Chain (Amplifiers and Data Converters)	14 - 22	↔	↔	
	Timing	16 - 26	↔	↔	
	Interface	16 - 20	↔	↔	
	Switching Regulators	16 - 28	↔	↔	
ROHM	Sensors	26 - 54	↔	↗	
	Switching Regulators	14 - 28	↔	↔	
ST Microelectronics	Sensors	22 - 36	↔	↔	
	Signal Chain (Amplifiers and Data Converters)	12 - 18	↔	↔	
	Multi - Source Analog/Power	12 - 20	↔	↔	
	Switching Regulators	12 - 22	↔	↔	
	Analog and Power for Automotive (CAN/LIN/Smart FET)	22 - 32	↔	↔	
TE Sensor Solutions	Sensors	18 - 54	↔	SMA	
Texas Instruments	Regulators	18 - 22	↔	↔	
	Sensors	18 - 22	↔	↔	
	Interface	18 - 22	↔	↔	
Vishay	Sensors	26 - 54	↗	↔	

Batteries

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Alium Batteries	Lithium Ion	22 - 24	↔	↔	
Energizer	Alkaline	12 - 14	↔	↔	
	Lithium Metal	16 - 18	↔	↔	
	Silver Oxide	10 - 12	↔	↔	
GP Batteries	Alkaline	16 - 18	↔	↗	
	Lithium Metal	20 - 22	↔	↗	
	Lithium Ion	18 - 20	↔	↗	
	Nickle Metal Hydride	12 - 14	↔	↔	
	Lead Acid	10 - 12	↔	↔	
	Carbon Zinc	10 - 12	↔	↔	
Panasonic	Alkaline	12 - 14	↔	↔	
	Lithium Metal	16 - 18	↔	↔	
	Nickle Metal Hydride	10 - 12	↔	↔	
	Carbon Zinc	10 - 12	↔	↔	
Rayovac	Alkaline	10 - 12	↔	↔	
	Lithium Metal	12 - 14	↔	↔	
	Nickle Metal Hydride	10 - 12	↔	↗	
	Carbon Zinc	10 - 12	↔	↔	
Renata Batteries	Lithium Metal	12 - 14	↔	↗	
	Lithium Ion	34 - 40	↔	↗	
	Nickle Metal Hydride	12 - 14	↔	↗	
	Silver Oxide	10 - 12	↔	↗	
	Carbon Zinc	10 - 12	↔	↗	
Tadiran Batteries	Lithium Metal	14 - 16	↔	↔	
	Alkaline	12 - 14	↔	↔	
	Lithium Metal	20 - 26	↔	↔	
VARTA	Lithium Ion	34 - 40	↔	↔	
	Nickle Metal Hydride	12 - 14	↔	↗	

Connectivity

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Abracon	Antennas	10 - 14	↔	↔	
AMS	RFID	22	↗	↔	
CEL	802.15.4/Zigbee Modules				
	Small Signal, Schottky Diodes, PIN Diodes, Bipolar Transistors, FETs/PHEMTs, Amplifiers, Mixers & Modulators, VCOs, SS Bipolar Transistors, Wideband Transistors	28 - 34	↔	↔	
		32	↔	↔	
Infineon & Cypress	Bluetooth Modules				
	Small Signal, Schottky Diodes, PIN Diodes, Bipolar Transistors, FETs/PHEMTs, Amplifiers, Mixers and Modulators, VCOs, SS Bipolar Transistors, Wideband Transistors	18 - 26	↔	↔	Cypress is now Infineon
		14 - 18	↔	↔	
Fibocom	Cellular Modules	14 - 18	↔	↔	
Kyocera AVX	Antennas	10 - 12	↔	↔	
Laird Connectivity	Wi-Fi Modules	18 - 38	↔	↔	
	Antennas	14 - 18	↗	↔	
	LoRa	32 - 54	↗	↔	
Linx Technologies	Cellular Modules	08 - 12	↔	↔	
	Antennas	10 - 14	↗	↔	
	Transceivers/Receivers	10 - 14	↗	↔	
Melexis	Transceivers/Receivers	18	↔	↔	
	RFID	16 - 18	↔	↔	
	Wi-Fi Modules	14 - 22	↔	↘	
Microchip	Bluetooth Modules	14 - 22	↔	↘	
	Transceivers/Receivers	14 - 22	↔	↔	
	LoRa	18	↔	↔	
MultiTech	Cellular Modules	14 - 18	↔	↔	
	LoRa	14 - 18	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Murata	Wi-Fi Modules				
	Bluetooth Modules	28 - 52	↔	↔	
	Small Signal, Schottky, Diodes, PIN Diodes, Bipolar, Transistors, FETs/PHEMTs, Amplifiers, Mixers and Modulators, VCOs, SS Bipolar Transistors, Wideband Transistors	28 - 52	↔	↔	
		14 - 22	↔	↔	
		32 - 42	↔	↔	
Nearson	LoRa				
	Antennas	10 - 12	↔	↔	
NXP	Multi-Protocol /Chip Solutions				
	Transceivers/Receivers	28 - 38	↔	↔	
	RFID	26	↔	↔	RFID Parts on allocation
	High Power IC's	16	↔	↔	
	Small Signal, Schottky Diodes, PIN Diodes, Bipolar Transistors, FETs/PHEMTs, Amplifiers, Mixers and Modulators, VCOs, SS Bipolar Transistors, Wideband Transistors	14 - 18	↔	↔	
		14 - 18	↔	↔	
Onsemi	Bluetooth Modules	18 - 32	↔	↔	
Panasonic	Bluetooth Modules	18 - 28	↔	↔	
	RFID	18 - 28	↔	↔	
Pulse Electronics	Antennas	10 - 12	↔	↔	
Semtech	Transceivers/Receivers	12 - 14	↔	↔	
	LoRa	10 - 18	↔	↔	
Sierra Wireless	Multi-Protocol /Chip Solutions	42 - 48	↔	↔	Intel based radios are at 52 weeks
	Cellular Modules	14 - 18	↔	↔	
Silex Technology	Wi-Fi Modules	22 - 42	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
ST Microelectronics	Bluetooth Modules	12 - 14	↔	↔	Capacity constraints on Spirit Radio ST25R39xx on allocation
	Transceivers/Receivers	14	↔	↔	
	RFID	22	↔	↔	
	GPS	14	↔	↔	
	High Power IC's	22 - 32	↔	↔	
	LoRa	12 - 14	↔	↔	
Synapse Wireless	802.15.4/Zigbee Modules	20 - 22	↔	↔	
Taoglas	Antennas	14 - 18	↔	↔	
TDK	Small Signal, Schottky Diodes				
	PIN Diodes, Bipolar Transistors, FETs/ PHEMTs, Amplifiers, Mixers and Modulators, VCOs, SS Bipolar Transistors, Wideband Transistors	14 - 22	↔	↔	
TE Connectivity	Cellular Modules	8 - 12	↔	↔	
	Antennas	10 - 12	↔	↔	
	Transceivers/Receivers	10 - 14	↔	↔	
Thales	Cellular Modules	14 - 22	↔	↔	
U-Blox	Bluetooth Modules	14 - 28	↔	↔	Phasing out their cellular product
	Cellular Modules	14 - 28	↔	↔	
	GPS	14 - 28	↔	↔	
	WiFiModules	14 - 28	↔	↔	

Discrete

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Diodes Inc.	Low Voltage MOSFETS	12 - 42	↗	SMA	
	TVS Diodes	10	↔	↔	
	Bridge Rectifiers	10 - 18	↔	SMA	
	Schottky Diodes	10 - 18	↔	↔	
	Rectifiers	10 - 16	↔	SMA	
	Switching Diodes	10 - 18	↔	↔	
	Small Signal MOSFETS	10 - 18	↔	↔	
	Zener Diodes	10 - 18	↔	↔	
	Bipolar Transistors	10 - 18	↔	↔	
	Digital Transistors	10 - 18	↔	↔	
	General Purpose Transistors	10 - 18	↔	↔	
EATON	Logic	10 - 12	↔	↔	
	ESD	12 - 14	↔	↔	
	Fuses	10 - 14	↔	↔	
Everlight	Clips and Holders	12 - 16	↔	↔	
	Optocoupler Components	16 - 20	↔	↔	
Fairchild	Rectifiers	18 - 52	↘	↔	
	Optocoupler Components	12 - 20	↔	↔	
Infineon	Low Voltage MOSFETS	12 - 24	↗	SMA	
	High Voltage MOSFETS	10 - 22	↗	SMA	
	IGBTs	14 - 44	↗	SMA	
	Wide Bandgap Mosfets	10 - 42	↔	↔	
	Digital Transistors	08 - 16	↔	↔	
	General Purpose Transistors	12 - 16	↔	↔	
Texas Instruments	Mil-Aero Transistors	20 - 28	↔	↗	
	Logic	18 - 22	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Isocom Components	Optocoupler Components	04 - 06	↔	↔	
IXYS	High Voltage MOSFETS	52 - 56	↔	↔	
	IGBTs	52 - 56	↔	↔	
Keystone	Clips and Holders	12 - 18	↔	SMA	
Kyocera	Varistors	16 - 20	↔	↔	
Lite-On	Optocoupler Components	14 - 16	↔	↔	
Littelfuse	ESD	12 - 14	↔	↔	
	Diode Arrays	12 - 14	↔	↔	
	Varistors	16 - 28	↔	↔	
	Wide Bandgap Mosfets	32 - 54	↔	↔	
	Fuses	10 - 14	↔	↔	
	PTC Fuses	10 - 14	↔	↔	
	Clips and Holders	12 - 14	↔	↔	
	Thyristors/Triacs	18 - 22	↔	↔	
	TVS Diodes	08 - 14	↔	↔	
	Sensors	18 - 32	↔	↔	
Micro Commercial Components	Low Voltage MOSFETS	12 - 26	↗	↔	
	High Voltage MOSFETS	14 - 32	↗	↔	
	ESD	12 - 14	↔	↔	
	TVS Diodes	12 - 10	↔	↔	
	Schottky Diodes	10 - 14	↗	↔	
	Switching Diodes	10 - 14	↗	↔	
	Small Signal Mosfets	12 - 16	↗	↔	
	Zener Diodes	12 - 16	↗	↔	
	Bipolar Transistors	10 - 16	↗	↔	
	General Purpose Transistors	10 - 16	↗	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Microchip	High Voltage Mosfets	06 - 28	↗	↔	
	Wide BandGap Mosfets	06 - 28	↔	↔	
Microsemi	High Voltage MOSFETS	44 - 54	↔	↔	
	IGBTs	44 - 54	↔	↔	
	Mil-Aero Diodes	28 - 54	↔	↔	
	Mil-Aero Transistors	34 - 62	↔	↔	
	Low Voltage MOSFETS	08 - 16	↗	SMA	
Nexperia	ESD	08 - 12	↔	↔	
	Schottky Diodes	08 - 10	↔	↔	
	Switching Diodes	08 - 10	↔	↔	
	Small Signal MOSFETS	08 - 10	↔	↔	
	Zener Diodes	08 - 10	↔	↔	
	Bipolar Transistors	08 - 10	↔	↔	
	Digital Transistors	08 - 10	↔	↔	
	General Purpose Transistors	08 - 10	↔	↔	
	Logic	08 - 10	↔	↔	
	Low Voltage MOSFETS	08 - 44	↗	SMA	
ON Semiconductor	High Voltage MOSFETS	06 - 24	↗	SMA	
	ESD	10 - 16	↗	↔	
	Wide Bandgap Mosfets	08 - 28	↔	SMA	
	Schottky Diodes	10 - 20	↔	↔	
	Rectifiers	10 - 14	↔	SMA	
	Switching Diodes	12 - 20	↔	↔	
	Small Signal MOSFETS	12 - 22	↔	↔	
	Zener Diodes	08 - 14	↔	↔	
	Bipolar Transistors	12 - 20	↔	↔	
	Digital Transistors	12 - 20	↔	↔	
	General Purpose Transistors	12 - 20	↘	↔	
	Logic	10 - 16	↘	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Schurter	Fuses	20 - 26	↔	↗	
	Clips and Holders	22 - 32	↔	↗	
Semtech	Diode Arrays	10 - 14	↔	↔	
ST Microelectronics	Low Voltage MOSFETS	16 - 28	↗	SMA	
	High Voltage MOSFETS	16 - 28	↗	SMA	
	IGBTs	16 - 28	↗	SMA	
	ESD	18 - 20	↘	↔	
	Wide Bandgap Mosfets	35 - 48	↔	SMA	
	Thyristors/Triacs	18 - 20	↔	↔	
	TVS Diodes	18 - 20	↔	↔	
	Rectifiers	16 - 18	↔	SMA	
	Bipolar Transistors	14 - 26	↔	↔	
TDK EPCOS	Varistors	16 - 22	↔	↔	
TE Connectivity	PTC Fuses	10 - 14	↔	↔	
Vishay	Low Voltage MOSFETS	10 - 42	↗	SMA	
	High Voltage MOSFETS	10 - 32	↗	SMA	
	TVS Diodes	10 - 14	↔	↔	
	Bridge Rectifiers	10 - 12	↔	SMA	
	Rectifiers	10 - 12	↔	SMA	
	Zener Diodes	12 - 16	↔	↔	
	Optocoupler Components	08 - 18	↔	↔	

Electromechanical

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Abracon	Timing	14 - 32	↙	SMA	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
ADDA	Fans	22 - 26	↔	↔	
Alps Electric	Switches	22 - 32	↔	↔	
American Zettler	Relays	18 - 32	↔	↔	
Bivar	Hardware	12 - 18	↔	↗	
Boyd	Fans	14 - 16	↔	↔	
	Heatsinks	18 - 26	↔	↔	
C&K	Switches	14 - 22	↔	↔	
Churod Electronics	Relays	16 - 26	↔	↔	
Citizen Finedevice	Timing	14 - 54	↔	↔	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
COSEL	Power Supplies (AC/DC)	14 - 38	↙	↔	
	Power Supplies (DC/DC)	14 - 38	↔	↔	
CTS	Switches	10 - 12	↔	↔	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
	Timing	12 - 32	↔	↔	
CUI Inc	Power Supplies (AC/DC)	16 - 30	↔	↔	
	Power Supplies (DC/DC)	14 - 30	↔	↔	
	Heatsinks	12 - 14	↔	↔	
Delta	Fans	26 - 34	↔	↔	
Diodes Inc	Timing	10 - 14	↔	↔	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
E-Switch	Switches	14 - 22	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
ECS Inc.	Timing	14 - 30	↔	↔	
EPSON Electronics America	Timing	14 - 28	↔	↔	
Essentra Components	Hardware	14 - 16	↔	↔	
Fox	Timing	12 - 14	↔	↔	
Grayhill	Switches	14 - 26	↔	↗	
Heyco	Hardware	12 - 14	↔	↗	
Hongfa	Relays	18 - 32	↔	↔	
Infineon	Relays	42 - 54	↔	↗	
IXYS	Relays	12 - 32	↔	↔	
Keystone	Hardware	14 - 16	↔	↔	
Kyocera International	Timing	12 - 32	↙	↔	
MEAN WELL	Power Supplies (AC/DC)	16 - 20	↔	↔	
Microchip	Timing	14 - 28	↔	↗	
Murata	Timing	10 - 12	↔	↔	
Murata Power Solutions	Power Supplies (AC/DC)	10 - 12	↔	↔	
NKK Switches	Switches	18 - 54	↔	↗	
NMB	Fans	28 - 42	↔	↔	
Ohmite	Fans	12 - 14	↔	↔	
Orion Fans	Fans	18 - 20	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Panasonic	Relays	16 - 32	↔	↗	
	Switches	12 - 14	↔	↔	
Qualtek	Fans	22 - 26	↔	↔	
Raltron	Timing	10 - 28	↔	↔	
RECOM	Power Supplies (AC/DC)	18 - 20	↔	↔	
	Power Supplies (DC/DC)	16 - 20	↔	↔	
Rosenberg	Fans	20 - 22	↔	↔	
Schneider Electric	Relays	18 - 20	↔	↔	
Song Chuan	Relays	26 - 38	↔	↔	
SUNON	Fans	26 - 28	↙	↔	
TE Connectivity Sensors	Relays	14 - 16	↔	↔	All stable except the IM ready Series allocation 52+ weeks
	Switches	12 - 14	↔	↔	
Vicor	Power Supplies (AC/DC)	28 - 54	↔	↔	
	Power Supplies (DC/DC)	28 - 54	↔	↔	
Wakefield Thermal	Heatsinks	12 - 14	↔	↔	
Wall Industries	Power Supplies (AC/DC)	10 - 12	↔	↔	
	Power Supplies (DC/DC)	10 - 12	↔	↔	
ZF Electronics	Switches	20 - 22	↔	↔	

High - End

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
AZ Displays	LCD'S	14 - 16	↔	↔	
Compulab	SOM	18	↔	↔	
Cypress	8 bit MCU	12 - 18	↔	↔	
	32 bit MCU	N/A	↔	↔	
	USB	N/A	↔	↔	
	Automotive	N/A	↔	↔	
Formerica	Fibre Optic Transceivers	14 - 18	↔	↔	
Infineon	Automotive	34 - 48	↔	↔	
iWave Systems	SOM	18	↔	↔	
Lattice Semiconductor	FPGA	18 - 26	↙	↙	
Microchip	8 bit MCU	06 - 14	↔	↔	
	32 bit MCU	06 - 20	↔	↔	
	PHY/Ethernet	08 - 14	↔	↔	
	USB	08 - 12	↔	↔	
	32 bit MPU	06 - 22	↔	↔	
Microsemi	FPGA	10 - 34	↔	↔	
NXP	8 bit MCU	15 - 42	↔	↔	
	32 bit MCU	15 - 42	↔	↔	
	Automotive	20 - 54	↔	↔	
	32 bit MPU	20 - 42	↔	↔	
	Network Processors	20 - 44	↔	↔	
Renesas RA	32 bit MCU	14 - 20	↗	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Renesas	8 bit MCU	14 - 20	↗	↔	
	32 bit MCU	14 - 20	↗	↔	
	Automotive	48	↔	↔	
	32 bit MPU	14	↔	↔	
Sharp	LCDs	30	↔	↔	
ST Microelectronics	8 bit MCU	12 - 26	↗	↔	
	Automotive	42 - 54	↔	↔	
	32 bit MPU	18 - 22	↔	↔	
	STEM32F0 - 32 bit MCU	12 - 14	↔	↔	
	STEM32F1 - 32 bit MCU	12 - 14	↔	↔	
	STEM32L - 32 bit MCU	15 - 18	↗	↘	
	Balance 32 bit MCU	15 - 18	↗	↘	
	STM32F2/F4/F7/H7	18 - 22	↗	↘	
Texas Instruments	MCUs & Processors	30 - 32	↔	↔	
Xilinx	FPGA	18 - 22	↔	↔	
Zilog	8 bit MCU	26 - 42	↔	↔	

Interconnect

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Adam Tech	I/O Connectors	18 - 20	↔	↔	
	PCB Connectors	18 - 20	↔	↔	
Altech Corp.	Terminal Blocks & Crimps	14	↔	↗	
Amphenol Communications Solutions	D-Sub Connectors	10 - 12	↔	↗	
	Data & Telecom	10 - 12	↔	↔	
	PCB Connectors	10 - 12	↔	↔	
	FFC/FPC	10 - 12	↔	↔	
Amphenol Sine System	Circular Connectors	10 - 22	↔	↔	
ASSMAN WSW Components	Data & Telecom	22	↔	↔	
	PCB Connectors	22	↔	↔	
	IC Sockets	22	↔	↔	
Bulgin	Circular Connectors	18 - 20	↔	↗	
EDAC	PCB Connectors	12 - 18	↔	↔	
Global Connector Technology	PCB Connectors	10 - 12	↔	↔	
	FFC/FPC	10 - 12	↔	↔	
HALO Electronics	Data & Telecom	14 - 20	↔	↔	
HARTING	PCB Connectors	12 - 14	↔	↔	
Hirose Electric	PCB Connectors	10 - 18	↔	↔	
	RF Connectors	10 - 18	↔	↔	
	FFC/FPC	10 - 18	↔	↔	
JST	PCB Connectors	18	↔	↔	
Mil-Max	PCB Connectors	06 - 08	↔	↔	
	IC Sockets	06 - 08	↔	↔	
Ouipiin	PCB Connectors	16 - 22	↔	↗	
Sullins	PCB Connectors	08 - 10	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
TE Connectivity	Automotive Connectors	14 - 18	↔	↗	
	Circular Connectors	14 - 18	↔	↗	
	Relays	14 - 18	↔	↗	
	Data & Telecom	14 - 18	↔	↗	
	PCB Connectors	14 - 18	↔	↗	
	RF Connectors	14 - 18	↔	↗	
	IC Sockets	14 - 18	↔	↗	
	Terminal Blocks & Crimps	14 - 18	↔	↗	
	Lighting Connectors	14 - 18	↔	↗	
WAGO	Terminal Blocks & Crimps	16	↔	↗	
	Lighting Connectors	16	↔	↔	
WECO	Terminal Blocks & Crimps	22 - 26	↗	↔	

Lighting solutions & Opto

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Bridgelux	Chip On Board (CoB)	08 - 10	↔	↔	
Dialight	Indication LEDs	12 - 18	↔	↔	
	6V (LED Optics)	12 - 18	↔	↔	
Everlight	Automotive LEDs (AEC-Q101 Certified)	10 - 12	↔	↔	
	Infrared Components/ LED	16 - 18	↔	↔	
	Indication LEDs	16 - 18	↔	↔	
	UV LEDs	10 - 12	↔	↔	
Excellence Optoelectronics Inc.	Automotive LEDs (AEC-Q101 Certified)	10 - 12	↔	↔	
General Luminaire	Standard Light Engines (Level 2 Boards)	16 - 18	↔	↔	
Inolux	Indication LEDs	08 - 10	↔	↔	
Kingbright	LED Displays	12 - 14	↔	↔	
	Indication LEDs	10 - 12	↔	↔	
	Infrared Components/ LED	16 - 18	↔	↔	
Lite-On	LED Displays	16 - 18	↔	↔	
	Indication LEDs	18 - 22	↔	↔	
Lumex	LED Displays	14	↔	↔	
	Indication LEDs	10 - 16	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Lumileds	Illumination High Power LEDs (White)				
	Illumination High Power LEDs (Colors)	10 - 16	↔	↔	
		10 - 16	↔	↔	
	Illumination High Power LEDs (White & Colors)	10 - 12	↔	↔	
	Horitcultural Mid Power LEDs (White & Colors)	10 - 12	↔	↔	
		16 - 18	↔	↔	
	Automotive LEDs (AEC-Q101 Certified)	10 - 12	↔	↔	
	Chip On Board (CoB)	20 - 28	↔	↔	
	Standard Light Engines (Level 2 Boards)	28	↔	↔	
		14 - 18	↔	↔	
	Infrared Components/ LED				
	UV LEDs				
Meanwell	LED Drivers	12 - 16	↔	↔	
Murata	Lighting Controls	28 - 32	↔	↔	
Nichia	Illumination High Power LEDs (White)				
		08 - 12	↔	↔	
	Illumination High Power LEDs (Colors)	08 - 12	↔	↔	
	Illumination High Power LEDs (White & Colors)	10 - 12	↔	↔	
		10 - 12	↔	↔	
	Horitcultural Mid Power LEDs (White & Colors)	14 - 16	↔	↔	
	Chip On Board (CoB)				
ROHM	Infrared Components/ LED	08 - 10	↔	↔	
	Indication LEDs	12 - 14	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Samsung LED	Illumination High Power LEDs (White)	08 - 10	↔	↔	
	Illumination High Power LEDs (White & Colors)	10 - 12	↔	↔	
	Horitcultural Mid Power LEDs (White & Colors)	10 - 12	↔	↔	
	Chip On Board (CoB)	08 - 10	↔	↔	
	Standard Light Engines (Level 2 Boards)	08-10	↔	↔	
Seoul Semiconductor	Illumination High Power LEDs (White)	08 - 10	↔	↔	
	Illumination High Power LEDs (White & Colors)	08 - 10	↔	↔	
	Horitcultural Mid Power LEDs (White & Colors)	08 - 10	↔	↔	
	Chip On Board (CoB)	10 - 12	↔	↔	
	Standard Light Engines (Level 2 Boards)	12 - 14	↔	↔	
Seoul Viosys	UV LEDs	10-18	↔	↔	
Stanley Electric	LED Displays	14	↔	↔	
	Indication LEDs	12 - 14	↔	↔	
TE Connectivity	6A (Heat Sinks, LED Holders)	14 - 22	↔	↔	
TT Electronics-Optek Technology	Infrared Components/ LED	28 - 46	↔	↔	
VCC	Indication LEDs	12-14	↔	↔	
Vishay	Infrared Components/ LED	10 - 22	↔	↔	
	Indication LEDs	10 - 32	↔	↔	
	UV LEDs	16 - 18	↔	↔	

Memory

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
ADATA	Memory Modules	08 - 10	↗	↗	
	eMMC	08 - 10	↗	↗	
	Memory Cards	10 - 12	↗	↗	
	Solid State Drives (SSD)	10 - 14	↗	↗	
Alliance Memory	PC (Commodity) DRAM	04 - 22	↔	↔	
	Mobile RAM	10 - 18	↔	↔	
	SRAM	10 - 32	↔	↔	
	NOR Flash	14 - 22	↔	↔	
	NAND Flash	10 - 26	↘	↔	
	eMMC	10 - 14	↔	↗	
Cypress	SRAM	14 - 54	↘	↔	
	NOR Flash	14 - 28	↘	↔	
	FRAM & NVSRAM	14 - 28	↘	↔	
Everspin Technologies	MRAM	14 - 20	↔	↔	
Greenliant	NOR Flash	10 - 18	↗	↗	
	eMMC	14 - 20	↗	↗	
	Memory Cards	10 - 18	↗	↗	
	Solid State Drives (SSD)	10 - 18	↗	↗	
Kingston	PC (Commodity) DRAM	04 - 06	↔	↔	
	Memory Modules	04 - 08	↗	↔	
	eMMC	06 - 08	↔	↗	
	Memory Cards	04 - 12	↗	↗	
	Solid State Drives (SSD)	06 - 10	↗	↗	
Macronix	NOR Flash	10 - 14	↔	↔	
	NAND Flash	10 - 14	↔	↔	
	eMMC	10 - 14	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Microchip	SRAM	06 - 14	↔	↔	
	NOR Flash	06 - 28	↔	↔	
	EEPROM	06 - 28	↔	↔	
	EPROM	14 - 28	↔	↗	
Onsemi	SRAM	22 - 42	↔	↔	
	EEPROM	14 - 22	↙	↔	
Renesas	SRAM	14 - 16	↙	↔	
	NOR FLASH	14 - 16	↙	↔	
	DATA FLASH	14 - 16	↙	↔	
Samsung LED	PC (Commodity) DRAM	54 - 56	↔	↔	Parts on allocation, Samsung is not quoting and not taking new orders for the time being
	Memory Modules	54 - 56	↔	↔	
	eMMC	54 - 56	↔	↔	
	Solid State Drivers (SSD)	54 - 56	↔	↔	
SkyHigh Memory	SLC NAND Flash	08 - 12	↙	↔	
	eMMC	10 - 14	↔	↔	
STMicroelectronics	EEPROM	06 - 10	↔	↔	Now on allocation

Passives

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Apl Delevan	Inductors	16 - 18	↔	↔	
Cornell Dubilier Electronics	Electrolytic	24 - 48	↔	↔	
	Capacitor	28 - 42	↔	↔	
CTS	Resistor Networks	18 - 22	↔	↗	
Eaton	Capacitors - Supercapacitors	12 - 22	↙	↔	
	Inductors	16 - 20	↔	↔	
ELNA	Capacitors - Supercapacitors	28 - 32	↙	↔	
HALO Electronics	Inductors	16 - 18	↔	↔	
Murata	Filters	14 - 18	↔	↔	
	Inductor / Transformers	14 - 22	↔	↔	
	Surface Mount General Capacitors - Ceramic (Less than 1 uf)	12 - 16	↔	↔	
	Surface Mount General Capacitors - Ceramic (Greater than 1 uf)	12 - 14	↔	↔	
	Leaded Capacitors - Ceramic	18 - 20	↔	↔	
	Specialty Capacitors	18	↔	↔	
	Surface Mount General Capacitors	16 - 18	↔	↔	
NIC Components	Electrolytic	16 - 22	↔	↔	
	Filters	16 - 22	↔	↔	
	Inductors	16 - 22	↔	↔	
	Fixed Resistors	14 - 20	↔	↔	
	Surface Mount General Capacitors - Ceramic (Greater than 1 uf)	20 - 22	↔	↔	
	Leaded Capacitors - Ceramic	14 - 16	↔	↔	
		28 - 30	↔	↔	
Nichicon	Electrolytic	24 - 32	↗	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Panasonic	Electrolytic	20 - 42	↗	↔	
	Capacitors - Polymer Tantalum	28 - 42	↔	↔	
	Inductors / Transformers	20 - 22	↔	↔	
	Fixed Resistors	22 - 32	↔	↔	
	Resistor Networks	20 - 30	↔	↔	
Paktron Capacitors	Capacitors - Film	14 - 18	↔	↔	
Samsung Electro-Mechanics	Fixed Resistors				
	Surface Mount General Capacitors- Ceramic (Less than 1 uf)v	46 - 48	↔	↔	
	Surface Mount General Capacitors – Ceramic (Greater than 1 uf)	46 - 48	↔	↔	
	Surface Mount General Capacitors-Ceramic *Automotive Upgrade	16 - 18	↔	↔	
Stackpole Electronics	Fixed Resistors	14 -16	↔	↔	
Sumida	Inductors	18 - 26	↔	↔	
Taiyo Yuden	Surface Mount General Capacitors- Ceramic (Less than 1 uf)	22 - 26	↔	↔	
	Surface Mount General	12 - 16	↔	↔	
	Capacitors- Ceramic (Greater than 1 uf)	22 - 24	↔	↔	
	Surface Mount General Capacitors - Ceramic *Automotive Upgrade	22 - 24	↔	↔	
TDK	Filters				
	Surface Mount General Capacitors - Ceramic (Less than 1 uf)	14 - 18	↔	↔	
	Surface Mount General Capacitors - Ceramic (Greater than 1 uf)	18 - 22	↘	↔	
	Surface Mount General Capacitors - Ceramic *Automotive Upgrade	22 - 26	↘	↔	
		22 - 26	↘	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
TDK EPCOS	Capacitors- Film	26 - 35	↙	↔	
	Filters	14 - 18	↔	↔	
	Inductors / Transformers	18 - 22	↔	↔	
TT Electronics - BI Technologies	Trimmers & Pots	18 - 22	↔	↗	
TT Electronics- IRC	Fixed Resistors	22 - 42	↔	↗	
United Chemi-Con	Electrolytic	24 - 36	↗	↔	
Viking	Surface Mount General Capacitors - Ceramic (Less than 1 uf)	14 - 16	↔	↔	
	Surface Mount General Capacitors - Ceramic (Greater than 1 uf)	14 - 16	↔	↔	
Vishay	Trimmers & Pots	12 - 22	↔	↔	
	Capacitors - Film	14 - 22	↔	↔	
	Capacitors - Supercapacitors	14 - 16	↔	↔	
	Capacitors - Tantalum Molded	14 - 18	↔	↔	
	Capacitors - Tantalum Conformals	18 - 20	↔	↔	
	Capacitors - Polymer Tantalum	24 - 42	↔	↔	AI Impact on Deliveries
	Inductors / Transformers	14 - 16	↔	↔	
	Fixed Resistors	12 - 22	↔	↔	
	Surface Mount General Capacitors - Ceramic (Less than 1 uf)	14 - 16	↙	↔	
	Leaded Capacitors - Ceramic	14 - 18	↙	↔	
	Specialty Capacitors	18 - 22	↙	↔	
WIMA	Capacitors - Film	14 - 18	↔	↔	
Würth Elektronik	Inductors / Transformers	20 - 22	↔	↔	
Yageo	Fixed Resistors				
	Resistor Networks	20 - 22	↔	↔	
	Surface Mount General Capacitors - Ceramic (Less than 1 uf)	22 - 26 24	↔ ↙	↔ ↔	Surface Mount General Capacitors - included transit time, shipment by boat
	Surface Mount General Capacitors Ceramic (Greater than 1 uf)	24	↙	↔	
	Surface Mount General Capacitors Ceramic *Automotive Upgrade	24	↙	↔	

Market Insights


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Jenny Ortila

Senior Commercial Analyst

The background is a dark navy blue. It features several thick, white, angular lines that intersect to form a series of geometric shapes, including a large triangle and various polygons, creating a modern, architectural feel.

Preventing problems in your supply chain

enquiries@reboundeu.com